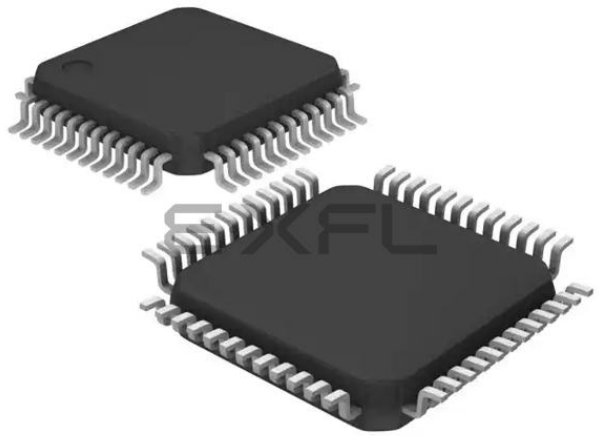

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What is "Embedded - Microcontrollers"?

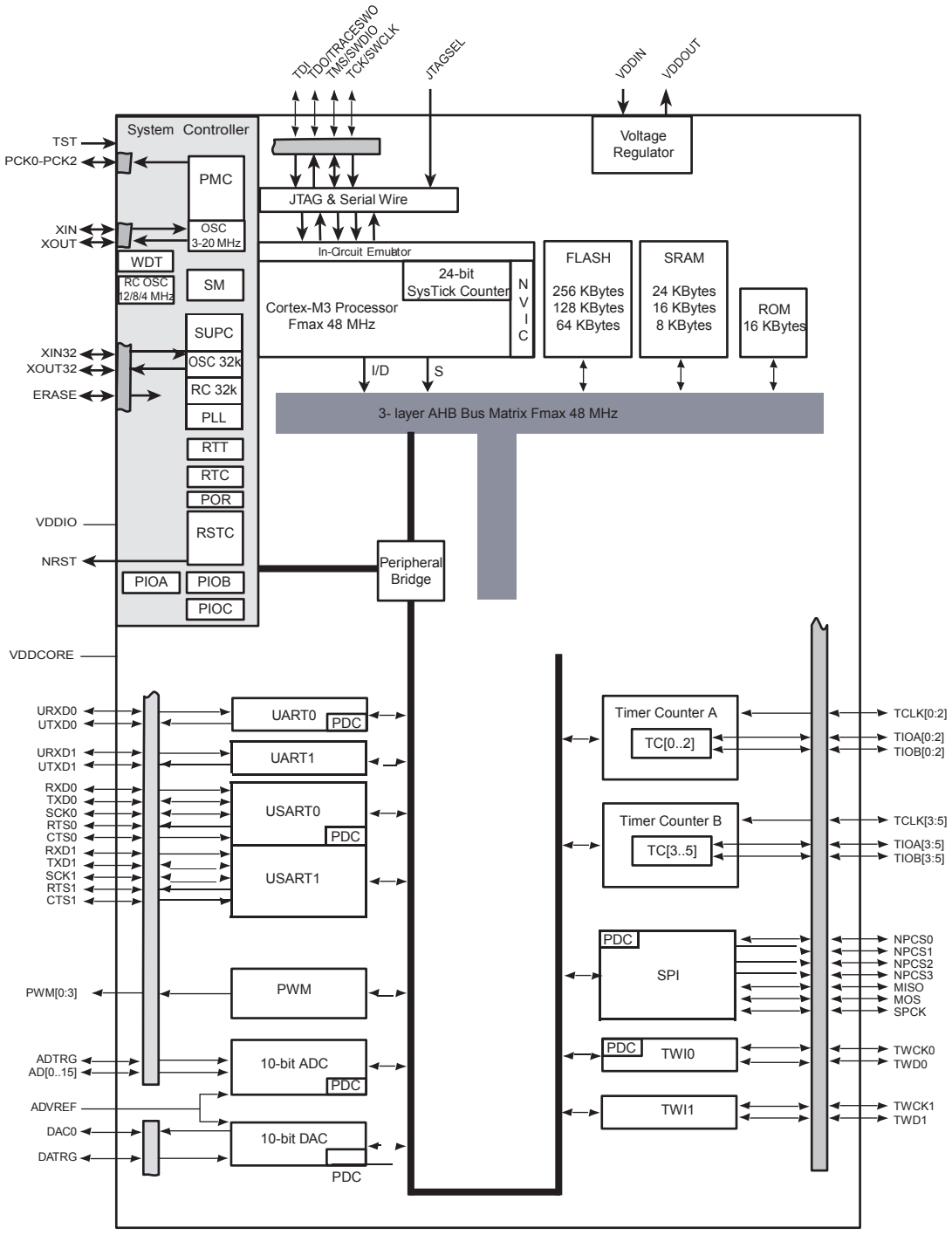
"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	ARM® Cortex®-M3
Core Size	32-Bit Single-Core
Speed	48MHz
Connectivity	I²C, IrDA, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, POR, PWM, WDT
Number of I/O	34
Program Memory Size	64KB (64K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	8K x 8
Voltage - Supply (Vcc/Vdd)	1.62V ~ 3.6V
Data Converters	A/D 8x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	48-LQFP
Supplier Device Package	48-LQFP (7x7)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/atsam3n1ab-au

2. SAM3N Block Diagram

Figure 2-1. SAM3N 100-pin version Block Diagram



4.1.4 100-ball TFBGA Pinout

Table 4-2. 100-ball TFBGA SAM3N4/2/1/0/00C Pinout

A1	PB1	C6	PB7	F1	PA18	H6	PC4
A2	PC29	C7	PC16	F2	PC26	H7	PA11
A3	VDDIO	C8	PA1	F3	VDDOUT	H8	PC1
A4	PB9	C9	PC17	F4	GND	H9	PA6
A5	PB8	C10	PA0	F5	VDDIO	H10	PB4
A6	PB13	D1	PB3	F6	PA27	J1	PC15
A7	PB11	D2	PB0	F7	PC8	J2	PC0
A8	PB10	D3	PC24	F8	PA28	J3	PA16
A9	PB6	D4	PC22	F9	TST	J4	PC6
A10	JTAGSEL	D5	GND	F10	PC9	J5	PA24
B1	PC30	D6	GND	G1	PA21	J6	PA25
B2	ADVREF	D7	VDDCORE	G2	PC27	J7	PA10
B3	GNDANA	D8	PA2	G3	PA15	J8	GND
B4	PB14	D9	PC11	G4	VDDCORE	J9	VDDCORE
B5	PC21	D10	PC14	G5	VDDCORE	J10	VDDIO
B6	PC20	E1	PA17	G6	PA26	K1	PA22
B7	PA31	E2	PC31	G7	PA12	K2	PC13
B8	PC19	E3	VDDIN	G8	PC28	K3	PC12
B9	PC18	E4	GND	G9	PA4	K4	PA20
B10	PB5	E5	GND	G10	PA5	K5	PC5
C1	PB2	E6	NRST	H1	PA19	K6	PC3
C2	VDDPLL	E7	PA29	H2	PA23	K7	PC2
C3	PC25	E8	PA30	H3	PC7	K8	PA9
C4	PC23	E9	PC10	H4	PA14	K9	PA8
C5	PB12	E10	PA3	H5	PA13	K10	PA7

4.2 SAM3N4/2/1/0/00B Package and Pinout

Figure 4-3. Orientation of the 64-pad QFN Package

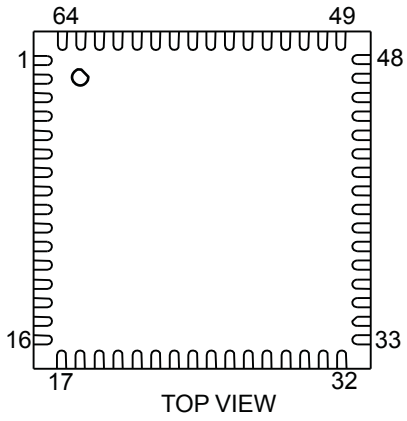
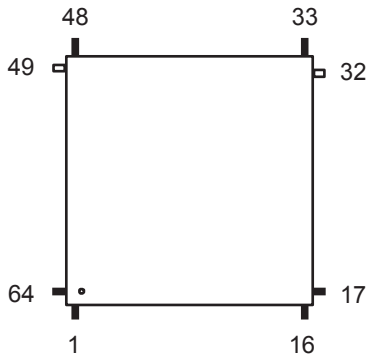


Figure 4-4. Orientation of the 64-lead LQFP Package



4.2.1 64-Lead LQFP and QFN Pinout

64-pin version SAM3N devices are pin-to-pin compatible with SAM3S products. Furthermore, SAM3N products have new functionalities shown in italic in Table 4-3.

Table 4-3. 64-pin SAM3N4/2/1/0/00B Pinout

1	ADVREF	17	GND	33	*TDI/PB4*	49	*TDO/TRACESWO/PB5*
2	GND	18	VDDIO	34	PA6/PGMNOE	50	JTAGSEL
3	*PB0/AD4*	19	PA16/PGMD4	35	PA5/PGMRDY	51	*TMS/SWDIO/PB6*
4	*PB1AD5*	20	PA15/PGMD3	36	PA4/PGMNCMD	52	PA31
5	*PB2/AD6*	21	PA14/PGMD2	37	PA27/PGMD15	53	*TCK/SWCLK/PB7*
6	*PB3/AD7*	22	PA13/PGMD1	38	PA28	54	VDDCORE
7	VDDIN	23	PA24/PGMD12	39	NRST	55	*ERASE/PB12*
8	VDDOUT	24	VDDCORE	40	TST	56	*PB10*
9	PA17/PGMD5/AD0	25	PA25/PGMD13	41	PA29	57	*PB11*
10	PA18/PGMD6/AD1	26	PA26/PGMD14	42	PA30	58	VDDIO
11	PA21/PGMD9/AD8	27	PA12/PGMD0	43	PA3	59	*PB13/DAC0*
12	VDDCORE	28	PA11/PGMM3	44	PA2/PGMEN2	60	GND
13	PA19/PGMD7/AD2	29	PA10/PGMM2	45	VDDIO	61	*XOUT/PB8*
14	PA22/PGMD10/AD9	30	PA9/PGMM1	46	GND	62	*XIN/PGMCK/PB9*
15	PA23/PGMD11	31	PA8/XOUT32/PGMM0	47	PA1/PGMEN1	63	*PB14*
16	PA20/PGMD8/AD3	32	PA7/XIN32/XOUT32/PGMNVALID	48	PA0/PGMEN0	64	VDDPLL

Note: The bottom pad of the QFN package must be connected to ground.

5. Power Considerations

5.1 Power Supplies

The SAM3N product has several types of power supply pins:

- VDDCORE pins: Power the core, including the processor, the embedded memories and the peripherals. Voltage ranges from 1.62V and 1.95V.
- VDDIO pins: Power the Peripherals I/O lines, Backup part, 32 kHz crystal oscillator and oscillator pads. Voltage ranges from 1.62V and 3.6V
- VDDIN pin: Voltage Regulator, ADC and DAC Power Supply. Voltage ranges from 1.8V to 3.6V for the Voltage Regulator
- VDDPLL pin: Powers the PLL, the Fast RC and the 3 to 20 MHz oscillators. Voltage ranges from 1.62V and 1.95V.

5.2 Voltage Regulator

The SAM3N embeds a voltage regulator that is managed by the Supply Controller.

This internal regulator is intended to supply the internal core of SAM3N. It features two different operating modes:

- In Normal mode, the voltage regulator consumes less than 700 µA static current and draws 60 mA of output current. Internal adaptive biasing adjusts the regulator quiescent current depending on the required load current. In Wait Mode quiescent current is only 7 µA.
- In Backup mode, the voltage regulator consumes less than 1 µA while its output (VDDOUT) is driven internally to GND. The default output voltage is 1.80V and the start-up time to reach Normal mode is less than100 µs.

For adequate input and output power supply decoupling/bypassing, refer to the Voltage Regulator section in the Electrical Characteristics section of the datasheet.

5.3 Typical Powering Schematics

The SAM3N supports a 1.62V-3.6V single supply mode. The internal regulator input connected to the source and its output feeds VDDCORE. Figure 5-1 shows the power schematics.

As VDDIN powers the voltage regulator and the ADC/DAC, when the user does not want to use the embedded voltage regulator, it can be disabled by software via the SUPC (note that it is different from Backup mode).

Figure 5-1. Single Supply

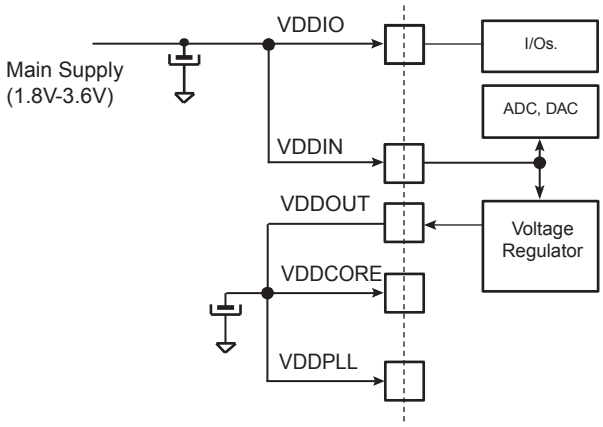
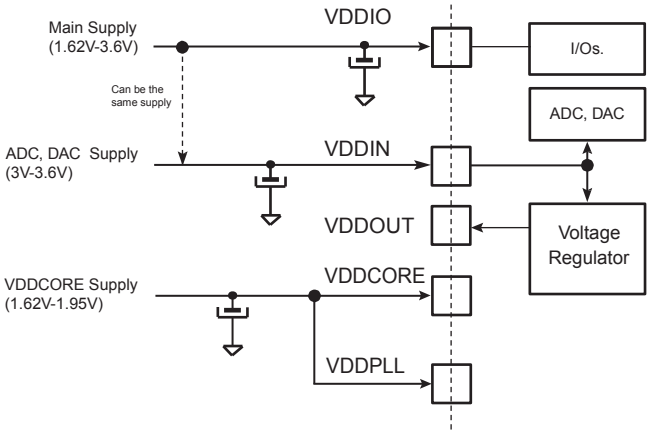


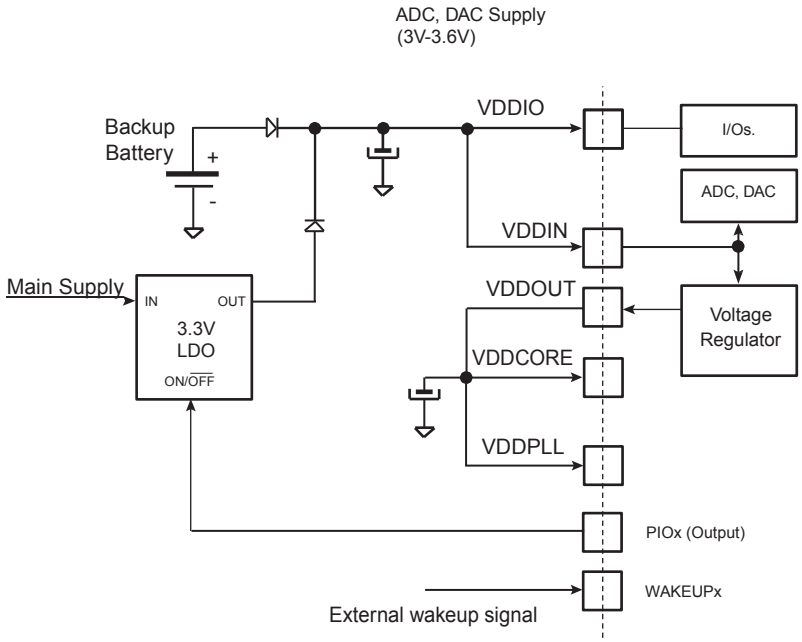
Figure 5-2. Core Externally Supplied



Note: Restrictions
With Main Supply < 3V, ADC and DAC are not usable.
With Main Supply >= 3V, all peripherals are usable.

Figure 5-3 below provides an example of the powering scheme when using a backup battery. Since the PIO state is preserved when in backup mode, any free PIO line can be used to switch off the external regulator by driving the PIO line at low level (PIO is input, pull-up enabled after backup reset). External wake-up of the system can be from a push button or any signal. See Section 5.6 “Wake-up Sources” for further details.TFBGA

Figure 5-3. Core Externally Supplied (backup battery)



Note: The two diodes provide a "switchover circuit" (for illustration purpose) between the backup battery and the main supply when the system is put in backup mode.

5.4 Active Mode

Active mode is the normal running mode with the core clock running from the fast RC oscillator, the main crystal oscillator or the PLL. The power management controller can be used to adapt the frequency and to disable the peripheral clocks.

5.5 Low Power Modes

The various low-power modes of the SAM3N are described below:

5.5.1 Backup Mode

The purpose of backup mode is to achieve the lowest power consumption possible in a system that is performing periodic wakeups to carry out tasks but not requiring fast startup time (<0.1ms). Total current consumption is 3 µA typical.

The Supply Controller, zero-power power-on reset, RTT, RTC, Backup registers and 32 kHz oscillator (RC or crystal oscillator selected by software in the Supply Controller) are running. The regulator and the core supply are off.

Backup mode is based on the Cortex-M3 deep sleep mode with the voltage regulator disabled.

The SAM3N can be awakened from this mode through WUP0-15 pins, the supply monitor (SM), the RTT or RTC wake-up event.

Backup mode is entered by using WFE instructions with the SLEEPDEEP bit in the System Control Register of the Cortex-M3 set to 1. (See the Power management description in The ARM Cortex M3 Processor section of the product datasheet).

Exit from Backup mode happens if one of the following enable wake-up events occurs:

- WKUPEN0-15 pins (level transition, configurable debouncing)

5.7 Fast Start-Up

The SAM3N allows the processor to restart in a few microseconds while the processor is in wait mode. A fast start up can occur upon detection of a low level on one of the 19 wake-up inputs (WKUP0 to 15 + SM + RTC + RTT).

The fast restart circuitry, as shown in Figure 5-5, is fully asynchronous and provides a fast start-up signal to the Power Management Controller. As soon as the fast start-up signal is asserted, the PMC automatically restarts the embedded 4 MHz fast RC oscillator, switches the master clock on this 4 MHz clock and reenables the processor clock.

Figure 5-5. Fast Start-Up Sources

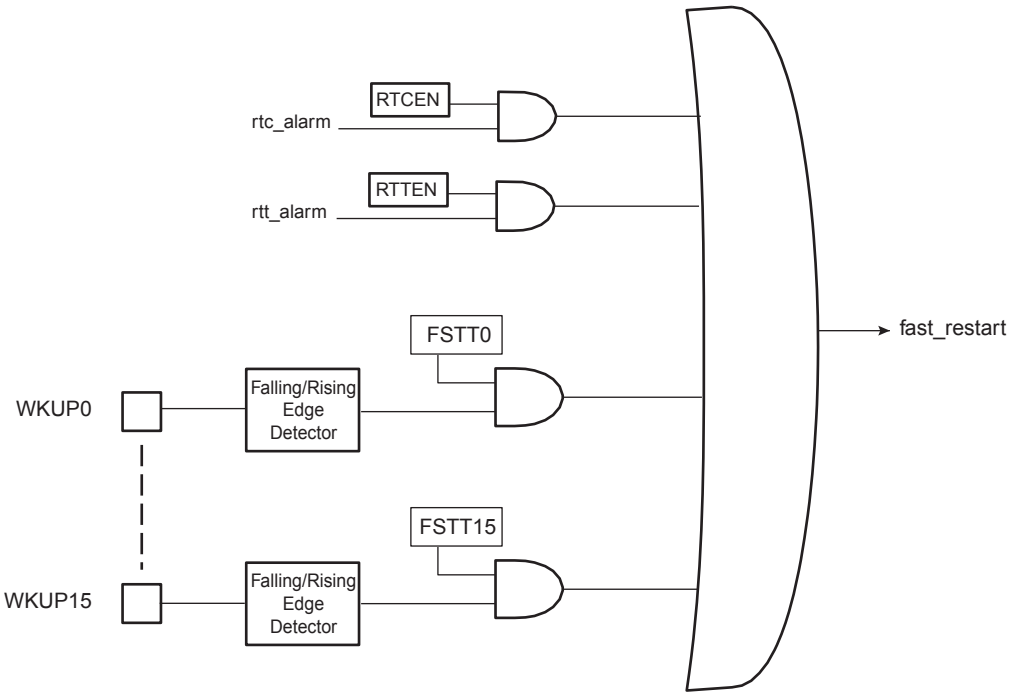


Table 6-1. System I/O Configuration Pin List.

SYSTEM_IO bit number	Default function after reset	Other function	Constraints for normal start	Configuration
12	ERASE	PB12	Low Level at startup(1)	In Matrix User Interface Registers (Refer to the System I/O Configuration Register in the Bus Matrix section of the product datasheet.)
7	TCK/SWCLK	PB7	-	
6	TMS/SWDIO	PB6	-	
5	TDO/TRACESWO	PB5	-	
4	TDI	PB4	-	
-	PA7	XIN32	-	See footnote (2) below
-	PA8	XOUT32	-	
-	PB9	XIN	-	See footnote (3) below
-	PB8	XOUT	-	

Notes:
1. If PB12 is used as PIO input in user applications, a low level must be ensured at startup to prevent Flash erase before the user application sets PB12 into PIO mode.
2. In the product Datasheet Refer to: Slow Clock Generator of the Supply Controller section.
3. In the product Datasheet Refer to: 3 to 20 MHZ Crystal Oscillator information in the PMC section.

6.2.1 Serial Wire JTAG Debug Port (SWJ-DP) Pins

The SWJ-DP pins are TCK/SWCLK, TMS/SWDIO, TDO/SWO, TDI and commonly provided on a standard 20-pin JTAG connector defined by ARM. For more details about voltage reference and reset state, refer to Table 3-1 on page 7.

At startup, SWJ-DP pins are configured in SWJ-DP mode to allow connection with debugging probe. Please refer to the Debug and Test Section of the product datasheet.

SWJ-DP pins can be used as standard I/Os to provide users more general input/output pins when the debug port is not needed in the end application. Mode selection between SWJ-DP mode (System IO mode) and general IO mode is performed through the AHB Matrix Special Function Registers (MATRIX_SFR). Configuration of the pad for pull-up, triggers, debouncing and glitch filters is possible regardless of the mode.

The JTAGSEL pin is used to select the JTAG boundary scan when asserted at a high level. It integrates a permanent pull-down resistor of about 15 kΩ to GND, so that it can be left unconnected for normal operations.

By default, the JTAG Debug Port is active. If the debugger host wants to switch to the Serial Wire Debug Port, it must provide a dedicated JTAG sequence on TMS/SWDIO and TCK/SWCLK which disables the JTAG-DP and enables the SW-DP. When the Serial Wire Debug Port is active, TDO/TRACESWO can be used for trace.

The asynchronous TRACE output (TRACESWO) is multiplexed with TDO. So the asynchronous trace can only be used with SW-DP, not JTAG-DP. For more information about SW-DP and JTAG-DP switching, please refer to the Debug and Test Section.

7.7 Debug and Test Features

- Debug access to all memory and registers in the system, including Cortex-M3 register bank when the core is running, halted, or held in reset.
- Serial Wire Debug Port (SW-DP) and Serial Wire JTAG Debug Port (SWJ-DP) debug access
- Flash Patch and Breakpoint (FPB) unit for implementing breakpoints and code patches
- Data Watchpoint and Trace (DWT) unit for implementing watchpoints, data tracing, and system profiling
- Instrumentation Trace Macrocell (ITM) for support of printf style debugging
- IEEE1149.1 JTAG Boundary-can on All Digital Pins

9. Memories

9.1 Embedded Memories

9.1.1 Internal SRAM

The SAM3N4 product embeds a total of 24-Kbytes high-speed SRAM.

The SAM3N2 product embeds a total of 16-Kbytes high-speed SRAM.

The SAM3N1 product embeds a total of 8-Kbytes high-speed SRAM.

The SRAM is accessible over System Cortex-M3 bus at address 0x2000 0000.

The SRAM is in the bit band region. The bit band alias region is from 0x2200 0000 and 0x23FF FFFF.

RAM size must be configurable by calibration fuses.

9.1.2 Internal ROM

The SAM3N product embeds an Internal ROM, which contains the SAM Boot Assistant (SAM-BA), In Application Programming routines (IAP) and Fast Flash Programming Interface (FFPI).

At any time, the ROM is mapped at address 0x0080 0000.

9.1.3 Embedded Flash

9.1.3.1 Flash Overview

The Flash of the SAM3N4 (256 Kbytes) is organized in one bank of 1024 pages of 256 bytes (Single plane).

The Flash of the SAM3N2 (128 Kbytes) is organized in one bank of 512 pages of 256 bytes (Single Plane).

The Flash of the SAM3N1 (64 Kbytes) is organized in one bank of 256 pages of 256 bytes (Single plane).

The Flash contains a 128-byte write buffer, accessible through a 32-bit interface.

9.1.3.2 Flash Power Supply

The Flash is supplied by VDDCORE.

9.1.3.3 Enhanced Embedded Flash Controller

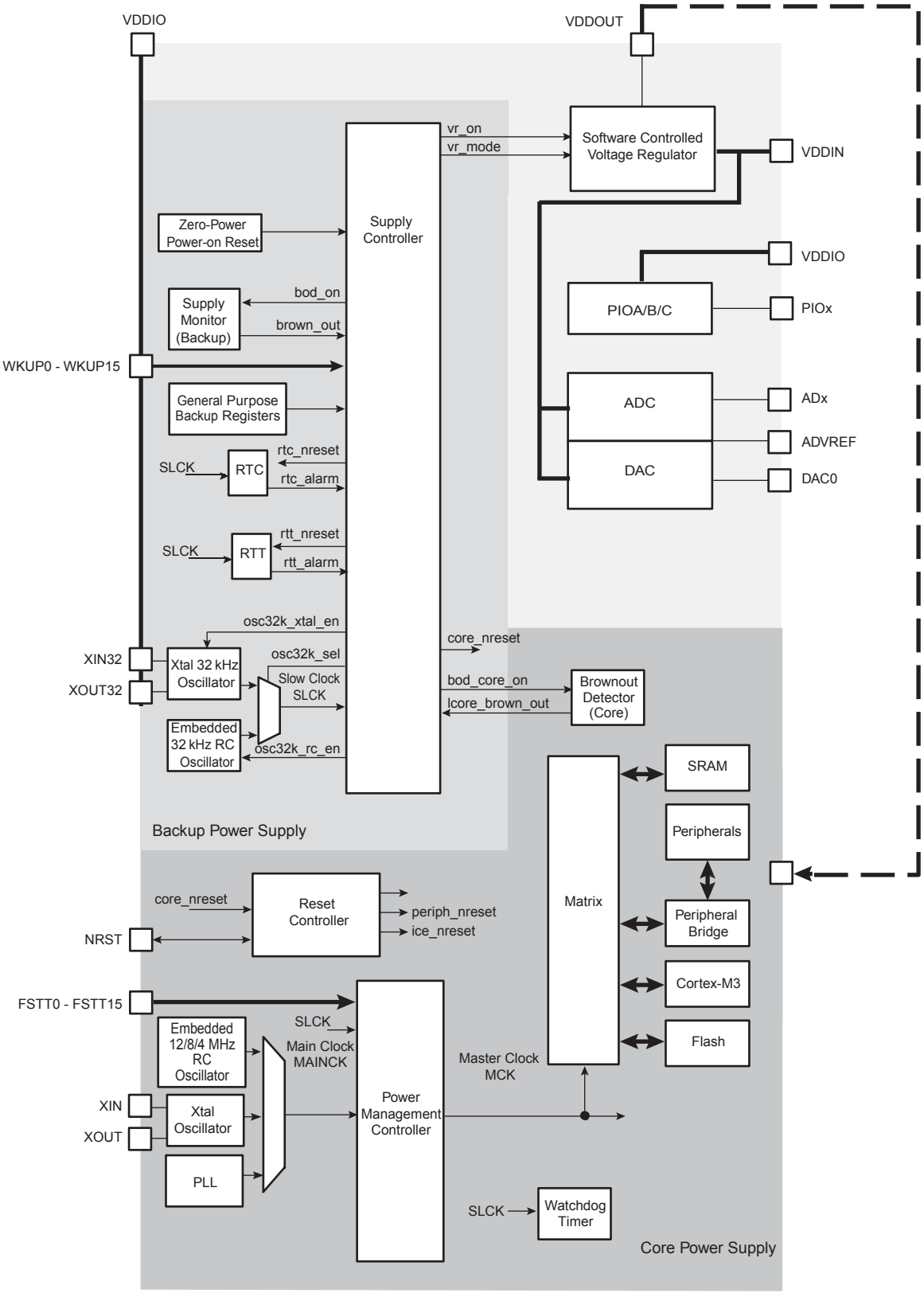
The Enhanced Embedded Flash Controller (EEFC) manages accesses performed by the masters of the system. It enables reading the Flash and writing the write buffer. It also contains a User Interface, mapped on the APB.

The Enhanced Embedded Flash Controller ensures the interface of the Flash block with the 32-bit internal bus. Its 128-bit wide memory interface increases performance.

The user can choose between high performance or lower current consumption by selecting either 128-bit or 64-bit access. It also manages the programming, erasing, locking and unlocking sequences of the Flash using a full set of commands.

One of the commands returns the embedded Flash descriptor definition that informs the system about the Flash organization, thus making the software generic.

Figure 10-1. System Controller Block Diagram



FSTT0 - FSTT15 are possible Fast Startup Sources, generated by WKUP0-WKUP15 Pins, but are not physical pins.

  - Multi-drive option enables driving in open drain
  - Programmable pull up on each I/O line
  - Pin data status register, supplies visibility of the level on the pin at any time
- Selection of the drive level
- Synchronous output, provides Set and Clear of several I/O lines in a single write

11. Peripherals

11.1 Peripheral Identifiers

Table 11-1 defines the Peripheral Identifiers of the SAM3N4/2/1/0/00. A peripheral identifier is required for the control of the peripheral interrupt with the Nested Vectored Interrupt Controller and for the control of the peripheral clock with the Power Management Controller.

Table 11-1. Peripheral Identifiers

Instance ID	Instance Name	NVIC Interrupt	PMC Clock Control	Instance Description
0	SUPC	**X**		**Supply Controller**
1	RSTC	**X**		Reset Controller
2	RTC	**X**		Real Time Clock
3	RTT	**X**		Real Time Timer
4	WDT	**X**		Watchdog Timer
5	PMC	**X**		Power Management Controller
6	EEFC	**X**		Enhanced Flash Controller
7	-	**-**		Reserved
8	UART0	**X**	**X**	UART 0
9	UART1	**X**	**X**	UART 1
10	-	**-**	**-**	Reserved
11	PIOA	**X**	**X**	Parallel I/O Controller A
12	PIOB	**X**	**X**	Parallel I/O Controller B
13	PIOC	**X**	**X**	Parallel I/O Controller C
14	USART0	**X**	**X**	USART 0
15	USART1	**X**	**X**	USART 1
16	-	**-**	**-**	Reserved
17	-	**-**	**-**	Reserved
18	-	**-**	**-**	Reserved
19	TWI0	**X**	**X**	Two Wire Interface 0
20	TWI1	**X**	**X**	Two Wire Interface 1
21	SPI	**X**	**X**	Serial Peripheral Interface
22	-	**-**	**-**	Reserved
23	TC0	**X**	**X**	Timer/Counter 0
24	TC1	**X**	**X**	Timer/Counter 1

Table 11-1. Peripheral Identifiers (Continued)

Instance ID	Instance Name	NVIC Interrupt	PMC Clock Control	Instance Description
25	TC2	**X**	**X**	Timer/Counter 2
26	TC3	**X**	**X**	Timer/Counter 3
27	TC4	**X**	**X**	Timer/Counter 4
28	TC5	**X**	**X**	Timer/Counter 5
29	ADC	**X**	**X**	Analog-to-Digital Converter
30	DACC	**X**	**X**	Digital-to-Analog Converter
31	PWM	**X**	**X**	Pulse Width Modulation

11.2 Peripheral Signals Multiplexing on I/O Lines

The SAM3N product features 2 PIO controllers (48-pin and 64-pin version) or 3 PIO controllers (100-pin version), PIOA, PIOB and PIOC, that multiplex the I/O lines of the peripheral set.

The SAM3N 64-pin and 100-pin PIO Controller controls up to 32 lines (see Table 10-2, “PIO available according to pin count,” on page 40). Each line can be assigned to one of three peripheral functions: A, B or C. The multiplexing tables in the following paragraphs define how the I/O lines of the peripherals A, B and C are multiplexed on the PIO Controllers. The column “Comments” has been inserted in this table for the user’s own comments; it may be used to track how pins are defined in an application.

Note that some peripheral functions which are output only, might be duplicated within the tables.

11.2.2 PIO Controller B Multiplexing

Table 11-3. Multiplexing on PIO Controller B (PIOB)

I/O Line	Peripheral A	Peripheral B	Peripheral C	Extra Function	System Function	Comments
PB0	PWM0			AD4		
PB1	PWM1			AD5		
PB2	URXD1	NPCS2		AD6/WKUP12		
PB3	UTXD1	PCK2		AD7		
PB4	TWD1	PWM2			TDI	
PB5	TWCK1			WKUP13	TDO/ TRACESWO	
PB6					TMS/SWDIO	
PB7					TCK/SWCLK	
PB8					XOUT	
PB9					XIN	
PB10						
PB11						
PB12					ERASE	
PB13		PCK0		DAC0		64/100-pin versions
PB14	NPCS1	PWM3				64/100-pin versions

12. Embedded Peripherals Overview

12.1 Serial Peripheral Interface (SPI)

- Supports communication with serial external devices
  - Four chip selects with external decoder support allow communication with up to 15 peripherals
  - Serial memories, such as DataFlash and 3-wire EEPROMs
  - Serial peripherals, such as ADCs, DACs, LCD Controllers, CAN Controllers and Sensors
  - External co-processors
- Master or slave serial peripheral bus interface
  - 8- to 16-bit programmable data length per chip select
  - Programmable phase and polarity per chip select
  - Programmable transfer delays between consecutive transfers and between clock and data per chip select
  - Programmable delay between consecutive transfers
  - Selectable mode fault detection
- Very fast transfers supported
  - Transfers with baud rates up to MCK
  - The chip select line may be left active to speed up transfers on the same device

12.2 Two Wire Interface (TWI)

- Master, Multi-Master and Slave Mode Operation
- Compatibility with Atmel two-wire interface, serial memory and I^2C compatible devices
- One, two or three bytes for slave address
- Sequential read/write operations
- Bit Rate: Up to 400 kbit/s
- General Call Supported in Slave Mode
- Connecting to PDC channel capabilities optimizes data transfers in Master Mode only (for TWI0 only)
  - One channel for the receiver, one channel for the transmitter
  - Next buffer support

12.3 Universal Asynchronous Receiver Transceiver (UART)

- Two-pin UART
  - Implemented features are 100% compatible with the standard Atmel USART
  - Independent receiver and transmitter with a common programmable Baud Rate Generator
  - Even, Odd, Mark or Space Parity Generation
  - Parity, Framing and Overrun Error Detection
  - Automatic Echo, Local Loopback and Remote Loopback Channel Modes

  - Support for two PDC channels with connection to receiver and transmitter (for UART0 only)

12.4 USART

- Programmable Baud Rate Generator
- 5- to 9-bit full-duplex synchronous or asynchronous serial communications
  - 1, 1.5 or 2 stop bits in Asynchronous Mode or 1 or 2 stop bits in Synchronous Mode
  - Parity generation and error detection
  - Framing error detection, overrun error detection
  - MSB- or LSB-first
  - Optional break generation and detection
  - By 8 or by-16 over-sampling receiver frequency
  - Hardware handshaking RTS-CTS
  - Receiver time-out and transmitter timeguard
  - Optional Multi-drop Mode with address generation and detection
- RS485 with driver control signal
- ISO7816, T = 0 or T = 1 Protocols for interfacing with smart cards (Only on USART0)
  - NACK handling, error counter with repetition and iteration limit
- SPI Mode
  - Master or Slave
  - Serial Clock programmable Phase and Polarity
  - SPI Serial Clock (SCK) Frequency up to MCK/4
- IrDA modulation and demodulation (Only on USART0)
  - Communication at up to 115.2 Kbps
- Test Modes
  - Remote Loopback, Local Loopback, Automatic Echo
- PDC support (for USART0 only)

12.5 Timer Counter (TC)

- Six 16-bit Timer Counter Channels
- Wide range of functions including:
  - Frequency Measurement
  - Event Counting
  - Interval Measurement
  - Pulse Generation
  - Delay Timing
  - Pulse Width Modulation
  - Up/down Capabilities
- Each channel is user-configurable and contains:
  - Three external clock inputs
  - Five internal clock inputs

Figure 13-3. 64and4B·leadLQFP Package Drawing

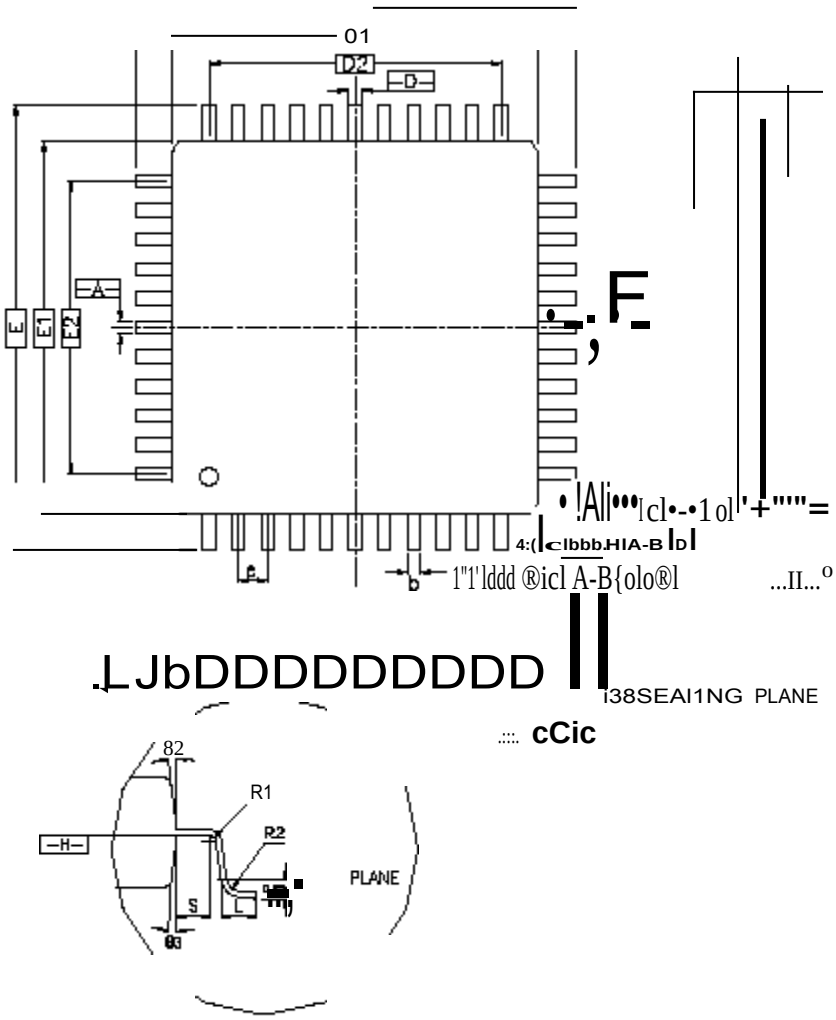


Table 13-2. 64-lead LQFP Package Dimensions (in mm)

Symbol	Millimeter			Inch		
	Min	**Nom**	**Max**	**Min**	**Nom**	**Max**
A	–	–	1.60	–	–	0.063
A1	0.05	–	0.15	0.002	–	0.006
A2	1.35	1.40	1.45	0.053	0.055	0.057
D	12.00 BSC			0.472 BSC		
D1	10.00 BSC			0.383 BSC		
E	12.00 BSC			0.472 BSC		
E1	10.00 BSC			0.383 BSC		
R2	0.08	–	0.20	0.003	–	0.008
R1	0.08	–	–	0.003	–	–
q	0°	3.5°	7°	0°	3.5°	7°
θ_1	0°	–	–	0°	–	–
θ_2	11°	12°	13°	11°	12°	13°
θ_3	11°	12°	13°	11°	12°	13°
c	0.09	–	0.20	0.004	–	0.008
L	0.45	0.60	0.75	0.018	0.024	0.030
L1	1.00 REF			0.039 REF		
S	0.20	–	–	0.008	–	–
b	0.17	0.20	0.27	0.007	0.008	0.011
e	0.50 BSC.			0.020 BSC.		
D2	7.50			0.285		
E2	7.50			0.285		
Tolerances of Form and Position						
aaa	0.20			0.008		
bbb	0.20			0.008		
ccc	0.08			0.003		
ddd	0.08			0.003		

Table 14-1.

Ordering Code	MRL	Flash (Kbytes)	Package	Package Type	Temperature Operating Range
ATSAM3N1AA-AU	A	64	LQFP48	Green	Industrial -40°C to 85°C
ATSAM3N1AB-AU	B	64	LQFP48	Green	Industrial -40°C to 85°C
ATSAM3N1AA-MU	A	64	QFN48	Green	Industrial -40°C to 85°C
ATSAM3N1AB-MU	B	64	QFN48	Green	Industrial -40°C to 85°C
ATSAM3N0CA-AU	A	32	LQFP100	Green	Industrial -40°C to 85°C
ATSAM3N0CA-CU	A	32	TFBGA100	Green	Industrial -40°C to 85°C
ATSAM3N0BA-AU	A	32	LQFP64	Green	Industrial -40°C to 85°C
ATSAM3N0BA-MU	A	32	QFN64	Green	Industrial -40°C to 85°C
ATSAM3N0AA-AU	A	32	LQFP48	Green	Industrial -40°C to 85°C
ATSAM3N0AA-MU	A	32	QFN48	Green	Industrial -40°C to 85°C
ATSAM3N00BA-AU	A	16	LQFP64	Green	Industrial -40°C to 85°C
ATSAM3N00BA-MU	A	16	QFN64	Green	Industrial -40°C to 85°C
ATSAM3N00AA-AU	A	16	LQFP48	Green	Industrial -40°C to 85°C
ATSAM3N00AA-MU	A	16	QFN48	Green	Industrial -40°C to 85°C